# TPS2291xx, 5.5-V, 2-A, 37mΩ On-Resistance Load Switch

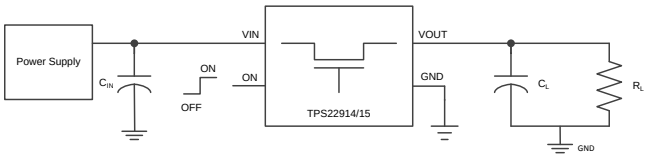
## 1 Features

- Integrated Single Channel Load Switch
- Input Voltage Range: 1.05 V to 5.5 V
- Low On-Resistance ($R_{ON}$)
  - $R_{ON}$ = 37 mΩ (Typ) at $V_{IN}$ = 5 V
  - $R_{ON}$ = 38 mΩ (Typ) at $V_{IN}$ = 3.3 V
  - $R_{ON}$ = 43 mΩ (Typ) at $V_{IN}$ = 1.8 V
- 2-A Maximum Continuous Switch Current
- Low Quiescent Current
  - 7.7 µA (typ) at $V_{IN}$ = 3.3 V
- Low Control Input Threshold Enables Use of 1.0-V or Higher GPIO
- Controlled Slew Rate
  - $t_R$(TPS22914B/15B) = 64 µs at $V_{IN}$ = 3.3 V
  - $t_R$(TPS22914C/15C) = 913 µs at $V_{IN}$ = 3.3 V
- Quick Output Discharge (TPS22915 only)
- Ultra-Small Wafer-Chip-Scale Package
  - 0.78 mm × 0.78 mm, 0.4-mm Pitch, 0.5-mm Height (YFP)
- ESD Performance Tested per JESD 22
  - 2-kV HBM and 1-kV CDM

## 2 Applications

- Smartphones / Mobile Phones
- Ultrathin / Ultrabook™ / Notebook PC
- Tablet PC / Phablet
- Wearable Technology
- Solid State Drives
- Digital Cameras

## 4 Simplified Schematic




## 3 Description

The TPS22914/15 is a small, low $R_{ON}$, single channel load switch with controlled slew rate. The device contains an N-channel MOSFET that can operate over an input voltage range of 1.05 V to 5.5 V and can support a maximum continuous current of 2 A. The switch is controlled by an on/off input, which is capable of interfacing directly with low-voltage control signals.

The small size and low $R_{ON}$ makes the device ideal for being used in space constrained, battery powered applications. The wide input voltage range of the switch makes it a versatile solution for many different voltage rails. The controlled rise time of the device greatly reduces inrush current caused by large bulk load capacitances, thereby reducing or eliminating power supply droop. The TPS22915 further reduces the total solution size by integrating a 143-Ω pull-down resistor for quick output discharge (QOD) when the switch is turned off.

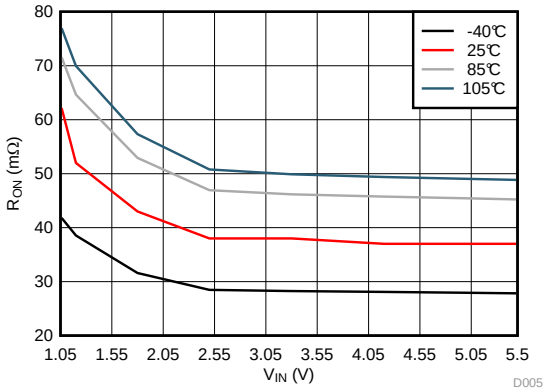
The TPS22914/15 is available in a small, space-saving 0.78 mm x 0.78 mm, 0.4-mm pitch, 0.5-mm height 4-pin Wafer-Chip-Scale (WCSP) package (YFP). The device is characterized for operation over the free-air temperature range of –40°C to 105°C.

**Device Information(1)**

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|---|---|---|
| TPS22914B | DSBGA (4) | 0.78 mm x 0.78 mm |
| TPS22914C | | |
| TPS22915B | | |
| TPS22915C | | |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

**$R_{ON}$ vs $V_{IN}$ ($I_{OUT}$ = –200 mA)**

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## 5 Revision History

**Changes from Revision B (September 2014) to Revision C** — **Page**

- Updated $T_A$ ratings in datasheet from 85°C to 105°C. ... 1

**Changes from Revision A (June 2014) to Revision B** — **Page**

- Updated X-axis scales in th Typical Characteristics section. ... 8

**Changes from Original (June 2014) to Revision A** — **Page**

- Initial release of full version. ... 1


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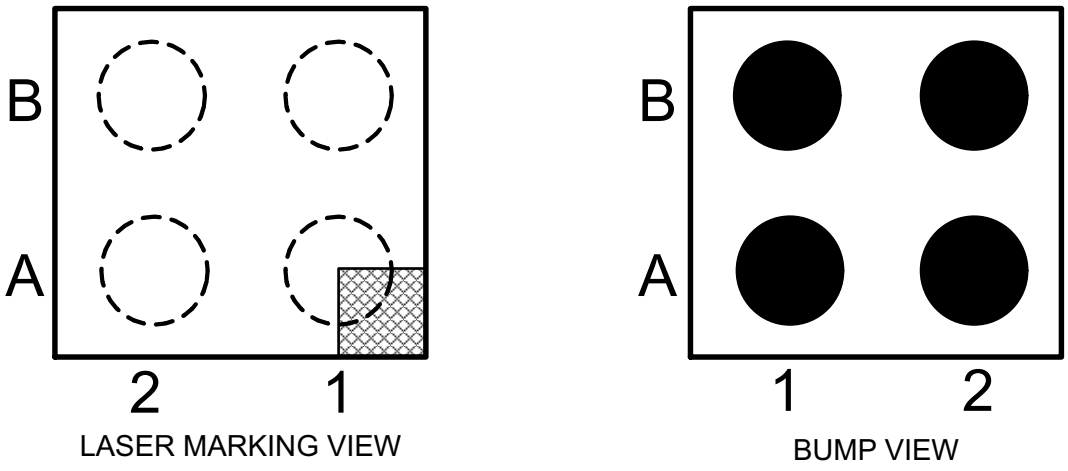
## 6 Device Comparison Table

| DEVICE | $R_{ON}$ at 3.3V (TYP) | $t_R$ at 3.3V (TYP) | QUICK OUTPUT DISCHARGE | MAXIMUM OUTPUT CURRENT | ENABLE |
|---|---|---|---|---|---|
| TPS22914B | 38 mΩ | 64 µs | No | 2 A | Active High |
| TPS22914C | 38 mΩ | 913 µs | No | 2 A | Active High |
| TPS22915B | 38 mΩ | 64 µs | Yes | 2 A | Active High |
| TPS22915C | 38 mΩ | 913 µs | Yes | 2 A | Active High |

## 7 Pin Configuration and Functions

**YFP PACKAGE**
**4 PIN DSBGA**
**TOP VIEW**




**Pin Description**

| | | |
|---|---|---|
| **B** | ON | GND |
| **A** | VIN | VOUT |
| | **2** | **1** |

**Pin Functions**

| PIN | | TYPE | DESCRIPTION |
|---|---|---|---|
| NAME | NO. | | |
| VOUT | A1 | O | Switch output. Place ceramic bypass capacitor(s) between this pin and GND. See the *Detailed Description* section for more information. |
| VIN | A2 | I | Switch input. Place ceramic bypass capacitor(s) between this pin and GND. See the *Detailed Description* section for more information. |
| GND | B1 | - | Device ground. |
| ON | B2 | I | Active high switch control input. Do not leave floating. |

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# 8 Specifications

## 8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1) (2)

| | | MIN | MAX | UNIT |
|---|---|---|---|---|
| $V_{IN}$ | Input voltage range | –0.3 | 6 | V |
| $V_{OUT}$ | Output voltage range | –0.3 | 6 | V |
| $V_{ON}$ | ON voltage range | –0.3 | 6 | V |
| $I_{MAX}$ | Maximum continuous switch current | | 2 | A |
| $I_{PLS}$ | Maximum pulsed switch current, pulse < 300 µs, 2% duty cycle | | 2.5 | A |
| $T_J$ | Maximum junction temperature | | 125 | °C |
| $T_{STG}$ | Storage temperature range | –65 | 150 | °C |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* . Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to network ground terminal.

## 8.2 ESD Ratings

| | | | VALUE | UNIT |
|---|---|---|---|---|
| $V_{(ESD)}$ | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1) | ±2000 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101(2) | ±1000 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

## 8.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{IN}$ | Input voltage range | | 1.05 | 5.5 | V |
| $V_{ON}$ | ON voltage range | | 0 | 5.5 | V |
| $V_{OUT}$ | Output voltage range | | | $V_{IN}$ | V |
| $V_{IH, ON}$ | High-level input voltage, ON | $V_{IN}$ = 1.05 V to 5.5 V | 1 | 5.5 | V |
| $V_{IL, ON}$ | Low-level input voltage, ON | $V_{IN}$ = 1.05 V to 5.5 V | 0 | 0.5 | V |
| $T_A$ | Operating free-air temperature range(1) | | –40 | 105 | °C |
| $C_{IN}$ | Input Capacitor | | 1(2) | | µF |

(1) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature [$T_{A(max)}$] is dependent on the maximum operating junction temperature [$T_{J(MAX)}$], the maximum power dissipation of the device in the application [$P_{D(MAX)}$], and the junction-to-ambient thermal resistance of the part/package in the application ($\theta_{JA}$), as given by the following equation: $T_{A(MAX)} = T_{J(MAX)} – (\theta_{JA} \times P_{D(MAX)})$.
(2) Refer to *Detailed Description* section

## 8.4 Thermal Information

| THERMAL METRIC(1) | | TPS2291x YFP (DSBGA) 4 PINS | UNIT |
|---|---|---|---|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 193 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 2.3 | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 36 | °C/W |
| $\psi_{JT}$ | Junction-to-top characterization parameter | 12 | °C/W |
| $\psi_{JB}$ | Junction-to-board characterization parameter | 36 | °C/W |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.


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## 8.5 Electrical Characteristics

Unless otherwise noted, the specification in the following table applies over the operating ambient temperature –40°C ≤ $T_A$ ≤ 105°C. **Typical values are for $T_A$ = 25°C.**

| PARAMETER | | TEST CONDITION | | $T_A$ | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| $I_{Q, VIN}$ | Quiescent current (TPS22914B/15B) | $V_{ON}$ = 5 V, $I_{OUT}$ = 0 A | $V_{IN}$ = 5.5 V | -40°C to 85°C | | 7.7 | 10.8 | µA |
| | | | | -40°C to 105°C | | | 12.1 | |
| | | | $V_{IN}$ = 5.0 V | -40°C to 85°C | | 7.6 | 9.6 | |
| | | | | -40°C to 105°C | | | 11.9 | |
| | | | $V_{IN}$ = 3.3 V | -40°C to 85°C | | 7.7 | 9.6 | |
| | | | | -40°C to 105°C | | | 12.0 | |
| | | | $V_{IN}$ = 1.8 V | -40°C to 85°C | | 8.4 | 11.0 | |
| | | | | -40°C to 105°C | | | 13.5 | |
| | | | $V_{IN}$ = 1.2 V | -40°C to 85°C | | 7.4 | 10.4 | |
| | | | | -40°C to 105°C | | | 13.9 | |
| | | | $V_{IN}$ = 1.05 V | -40°C to 85°C | | 6.7 | 10.9 | |
| | | | | -40°C to 105°C | | | 11.7 | |
| | Quiescent current (TPS22914C/15C) | $V_{ON}$ = 5 V, $I_{OUT}$ = 0 A | $V_{IN}$ = 5.5 V | -40°C to 85°C | | 7.7 | 11.5 | µA |
| | | | | -40°C to 105°C | | | 14.1 | |
| | | | $V_{IN}$ = 5.0 V | -40°C to 85°C | | 7.6 | 11.1 | |
| | | | | -40°C to 105°C | | | 13.7 | |
| | | | $V_{IN}$ = 3.3 V | -40°C to 85°C | | 7.7 | 10.7 | |
| | | | | -40°C to 105°C | | | 13.3 | |
| | | | $V_{IN}$ = 1.8 V | -40°C to 85°C | | 8.4 | 11.7 | |
| | | | | -40°C to 105°C | | | 13.4 | |
| | | | $V_{IN}$ = 1.2 V | -40°C to 85°C | | 7.4 | 11.0 | |
| | | | | -40°C to 105°C | | | 12.8 | |
| | | | $V_{IN}$ = 1.05 V | -40°C to 85°C | | 6.7 | 10.9 | |
| | | | | -40°C to 105°C | | | 10.9 | |
| $I_{SD, VIN}$ | Shutdown current | $V_{ON}$ = 0 V, $V_{OUT}$ = 0 V | $V_{IN}$ = 5.5 V | -40°C to 85°C | | 0.5 | 2 | µA |
| | | | | -40°C to 105°C | | | 3 | |
| | | | $V_{IN}$ = 5.0 V | -40°C to 85°C | | 0.5 | 2 | |
| | | | | -40°C to 105°C | | | 3 | |
| | | | $V_{IN}$ = 3.3 V | -40°C to 85°C | | 0.5 | 2 | |
| | | | | -40°C to 105°C | | | 3 | |
| | | | $V_{IN}$ = 1.8 V | -40°C to 85°C | | 0.5 | 2 | |
| | | | | -40°C to 105°C | | | 3 | |
| | | | $V_{IN}$ = 1.2 V | -40°C to 85°C | | 0.4 | 2 | |
| | | | | -40°C to 105°C | | | 3 | |
| | | | $V_{IN}$ = 1.05 V | -40°C to 85°C | | 0.4 | 2 | |
| | | | | -40°C to 105°C | | | 3 | |
| $I_{ON}$ | ON pin input leakage current | $V_{IN}$ = 5.5 V, $I_{OUT}$ = 0 A | | -40°C to 105°C | | | 0.1 | µA |

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## Electrical Characteristics (continued)

Unless otherwise noted, the specification in the following table applies over the operating ambient temperature –40°C ≤ $T_A$ ≤ 105°C. **Typical values are for $T_A$ = 25°C.**

| PARAMETER | | TEST CONDITION | $T_A$ | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $R_{ON}$ | On-Resistance | $V_{IN}$ = 5.5 V, $I_{OUT}$ = –200 mA | 25°C | | 37 | 40 | mΩ |
| | | | -40°C to 85°C | | | 51 | |
| | | | -40°C to 105°C | | | 57 | |
| | | $V_{IN}$ = 5.0 V, $I_{OUT}$ = –200 mA | 25°C | | 37 | 41 | mΩ |
| | | | -40°C to 85°C | | | 51 | |
| | | | -40°C to 105°C | | | 57 | |
| | | $V_{IN}$ = 4.2 V, $I_{OUT}$ = –200 mA | 25°C | | 37 | 41 | mΩ |
| | | | -40°C to 85°C | | | 52 | |
| | | | -40°C to 105°C | | | 58 | |
| | | $V_{IN}$ = 3.3 V, $I_{OUT}$ = –200 mA | 25°C | | 38 | 41 | mΩ |
| | | | -40°C to 85°C | | | 52 | |
| | | | -40°C to 105°C | | | 59 | |
| | | $V_{IN}$ = 2.5 V, $I_{OUT}$ = –200 mA | 25°C | | 38 | 42 | mΩ |
| | | | -40°C to 85°C | | | 53 | |
| | | | -40°C to 105°C | | | 58 | |
| | | $V_{IN}$ = 1.8 V, $I_{OUT}$ = –200 mA | 25°C | | 43 | 48 | mΩ |
| | | | -40°C to 85°C | | | 59 | |
| | | | -40°C to 105°C | | | 66 | |
| | | $V_{IN}$ = 1.2 V, $I_{OUT}$ = –200 mA | 25°C | | 52 | 61 | mΩ |
| | | | -40°C to 85°C | | | 73 | |
| | | | -40°C to 105°C | | | 85 | |
| | | $V_{IN}$ = 1.05 V, $I_{OUT}$ = –200 mA | 25°C | | 63 | 96 | mΩ |
| | | | -40°C to 85°C | | | 102 | |
| | | | -40°C to 105°C | | | 107 | |
| $V_{HYS}$ | ON pin hysteresis | $V_{IN}$ = 5.5 V | 25°C | | 102 | | mV |
| | | $V_{IN}$ = 5.0 V | | | 100 | | |
| | | $V_{IN}$ = 3.3 V | | | 98 | | |
| | | $V_{IN}$ = 2.5 V | | | 96 | | |
| | | $V_{IN}$ = 1.8 V | | | 96 | | |
| | | $V_{IN}$ = 1.2 V | | | 94 | | |
| | | $V_{IN}$ = 1.05 V | | | 92 | | |
| $R_{PD}$ (1) | Output pull down resistor | $V_{IN}$ = $V_{OUT}$ = 3.3 V, $V_{ON}$ = 0 V | -40°C to 105°C | | 143 | 200 | Ω |

(1) TPS22915B only.


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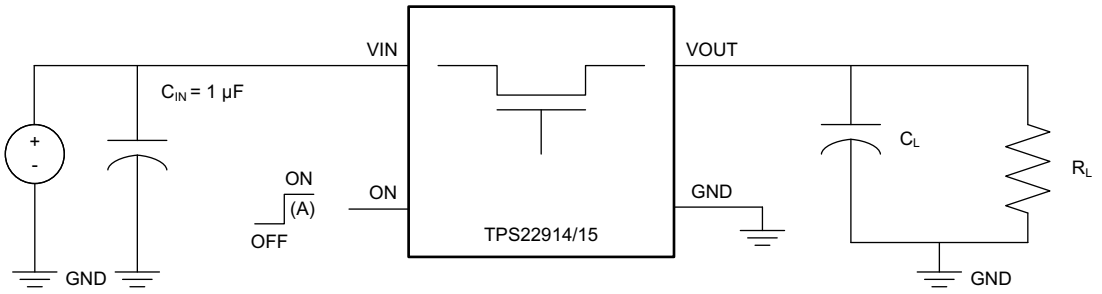
## 8.6 Switching Characteristics

Refer to the timing test circuit in Figure 1 (unless otherwise noted) for references to external components used for the test condition in the switching characteristics table. Switching characteristics shown below are only valid for the power-up sequence where VIN is already in steady state condition before the ON pin is asserted high.

| PARAMETER | | TEST CONDITION | TYP (TPS22914B/15B) | TYP (TPS22914C/15C) | UNIT |
|---|---|---|---|---|---|
| **$V_{IN}$ = 5 V, $V_{ON}$ = 5 V, $T_A$ = 25°C (unless otherwise noted)** | | | | | |
| $t_{ON}$ | Turn-on time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 104 | 1300 | µs |
| $t_{OFF}$ | Turn-off time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 2 | 2 | µs |
| $t_R$ | $V_{OUT}$ rise time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 89 | 1277 | µs |
| $t_F$ | $V_{OUT}$ fall time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 2 | 2 | µs |
| $t_D$ | Delay time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 59 | 663 | µs |
| **$V_{IN}$ = 3.3 V, $V_{ON}$ = 5 V, $T_A$ = 25°C (unless otherwise noted)** | | | | | |
| $t_{ON}$ | Turn-on time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 83 | 1077 | µs |
| $t_{OFF}$ | Turn-off time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 2 | 2 | µs |
| $t_R$ | $V_{OUT}$ rise time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 64 | 913 | µs |
| $t_F$ | $V_{OUT}$ fall time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 2 | 2 | µs |
| $t_D$ | Delay time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 52 | 622 | µs |
| **$V_{IN}$ = 1.05 V, $V_{ON}$ = 5 V, $T_A$ = 25°C (unless otherwise noted)** | | | | | |
| $t_{ON}$ | Turn-on time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 61 | 752 | µs |
| $t_{OFF}$ | Turn-off time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 3 | 3 | µs |
| $t_R$ | $V_{OUT}$ rise time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 28 | 409 | µs |
| $t_F$ | $V_{OUT}$ fall time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 2 | 2 | µs |
| $t_D$ | Delay time | $R_L$ = 10 Ω, $C_{IN}$ = 1 µF, $C_{OUT}$ = 0.1 µF | 47 | 547 | µs |




A. Rise and fall times of the control signal is 100ns

**Figure 1. Test Circuit**

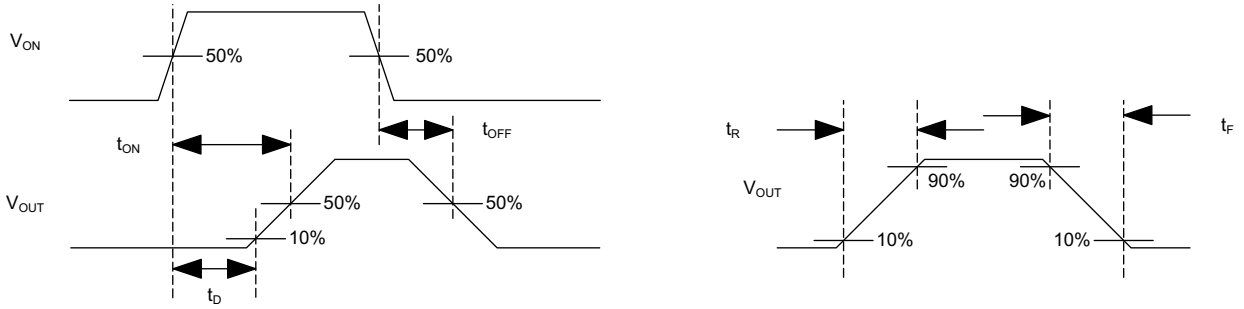
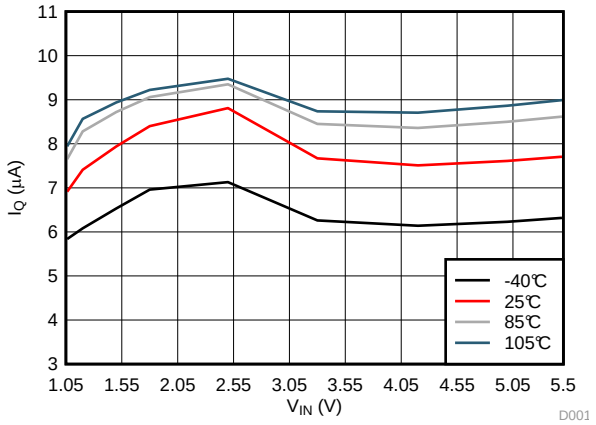


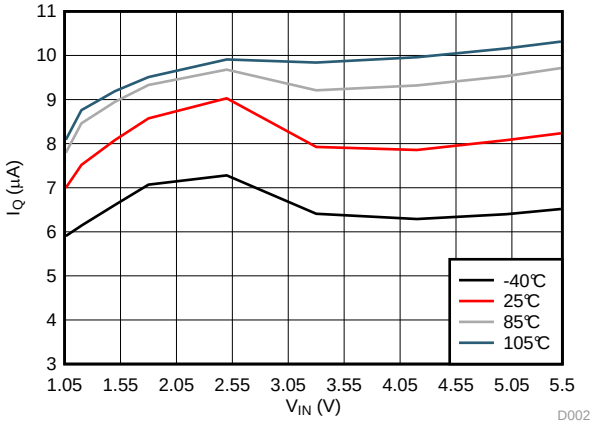

**Figure 2. Timing Waveforms**

## 8.7 Typical DC Characteristics



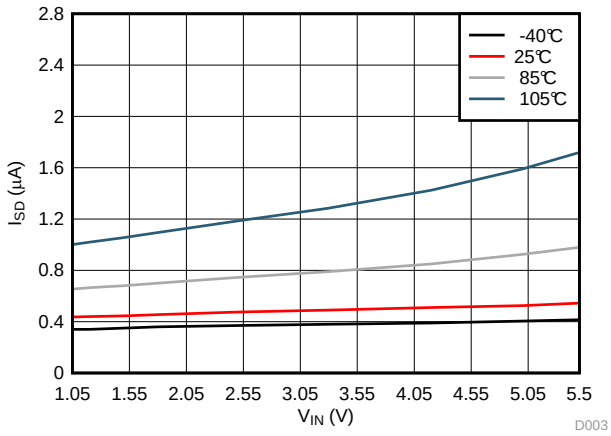

$V_{ON}$ = 5 V $I_{OUT}$ = 0 A

**Figure 3. $I_Q$ vs $V_{IN}$ (TPS22914B/15B)**



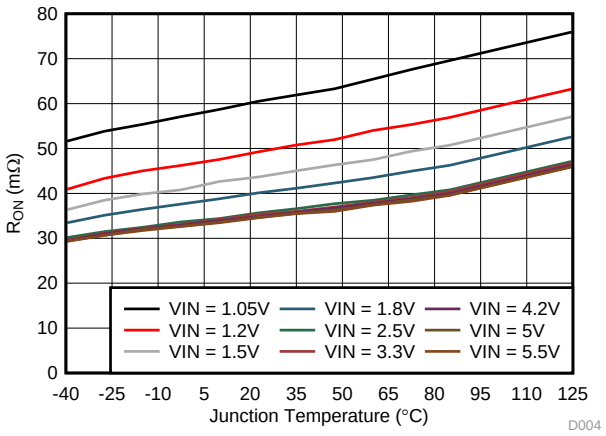

$V_{ON}$ = 5 V $I_{OUT}$ = 0 A

**Figure 4. $I_Q$ vs $V_{IN}$ (TPS22914C/15C)**



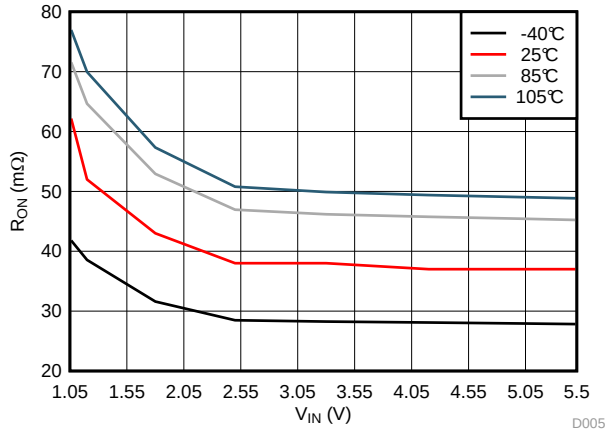

$V_{ON}$ = 0 V $I_{OUT}$ = 0 A

**Figure 5. $I_{SD}$ vs $V_{IN}$**



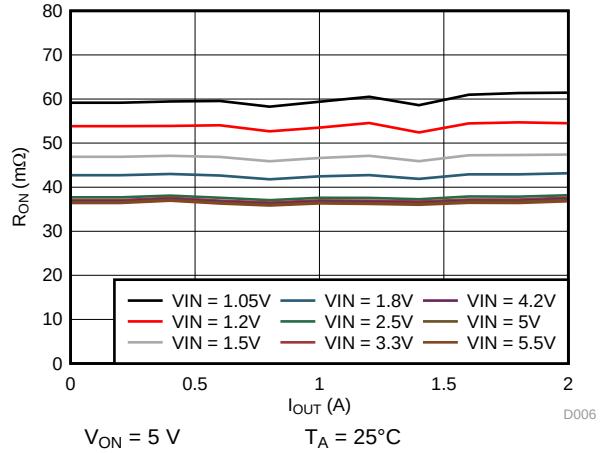

$V_{ON}$ = 5 V $I_{OUT}$ = –200 mA

**Figure 6. $R_{ON}$ vs $T_J$**




$V_{ON}$ = 5 V $I_{OUT}$ = –200 mA

**Figure 7. $R_{ON}$ vs $V_{IN}$**




$V_{ON}$ = 5 V $T_A$ = 25°C

**Figure 8. $R_{ON}$ vs $I_{OUT}$**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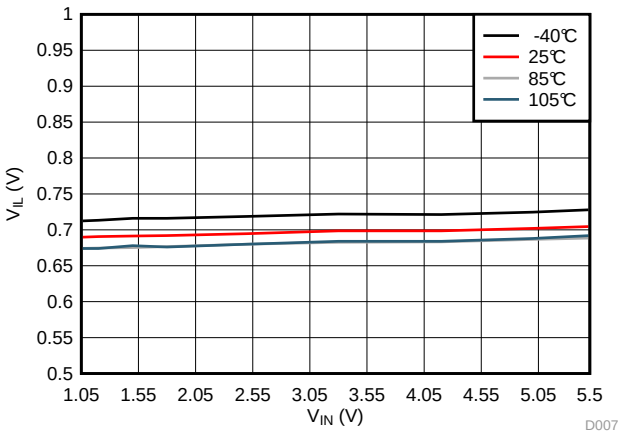
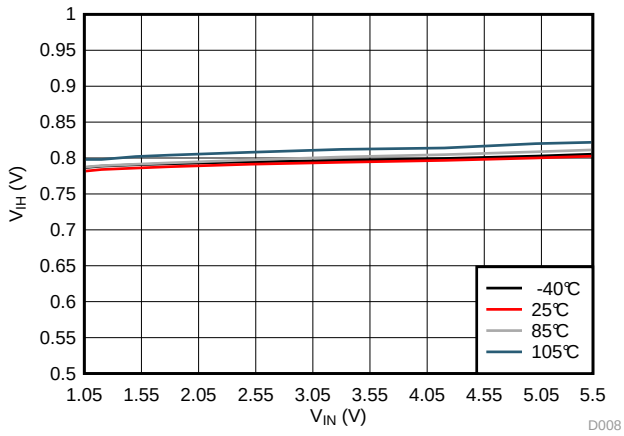
## Typical DC Characteristics (continued)



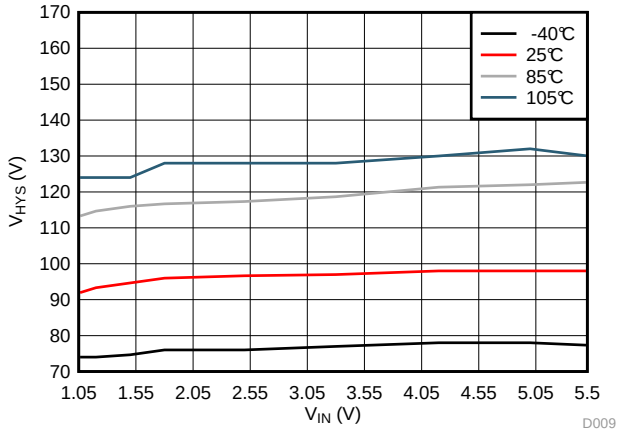

$I_{OUT}$ = 0 A

**Figure 9. $V_{IL}$ vs $V_{IN}$**



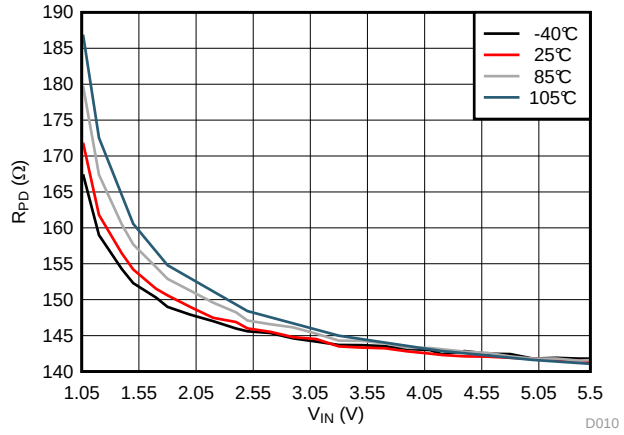

$I_{OUT}$ = 0 A

**Figure 10. $V_{IH}$ vs $V_{IN}$**




$I_{OUT}$ = 0 A

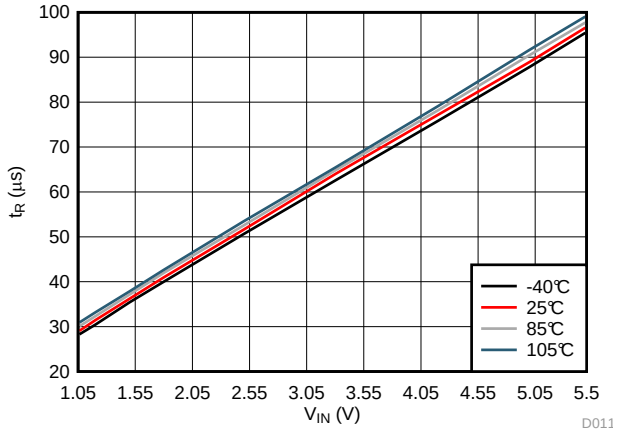
**Figure 11. $V_{HYS}$ vs $V_{IN}$**




$V_{IN}$ = $V_{OUT}$ $V_{ON}$ = 0 V

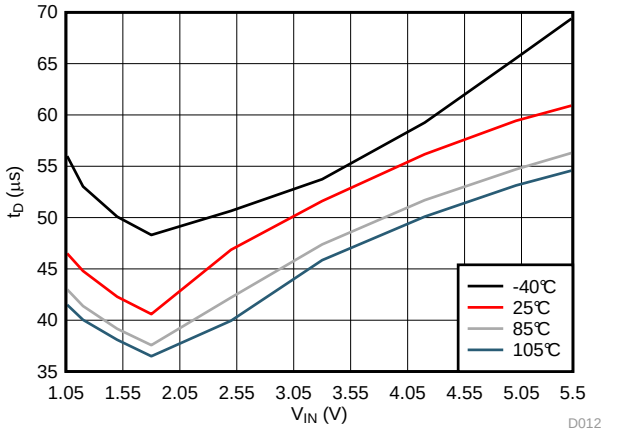
**Figure 12. $R_{PD}$ vs $V_{IN}$**

## 8.8 Typical AC Characteristics (TPS22914B/15B)



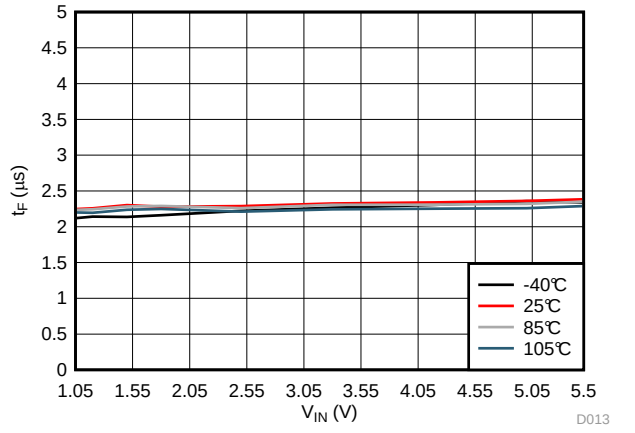

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 13. $t_R$ vs $V_{IN}$**



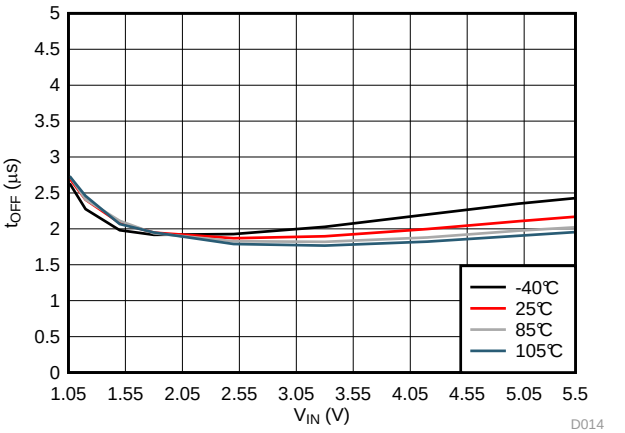

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 14. $t_D$ vs $V_{IN}$**



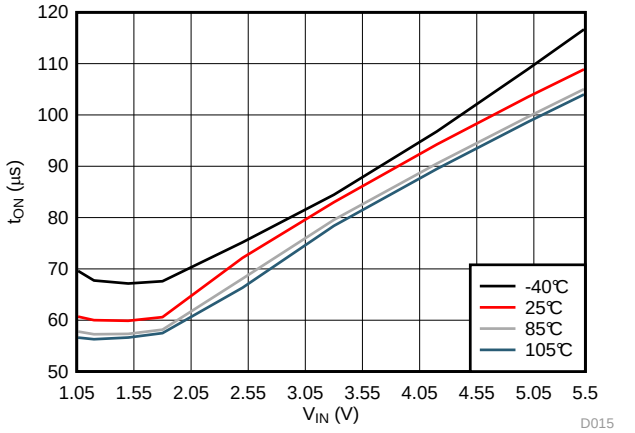

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 15. $t_F$ vs $V_{IN}$**



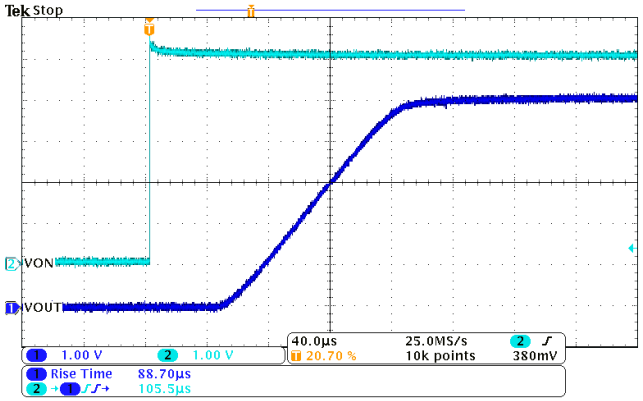

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 16. $t_{OFF}$ vs $V_{IN}$**




$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 17. $t_{ON}$ vs $V_{IN}$**




$V_{IN}$ = 5 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 18. $t_R$ at $V_{IN}$ = 5 V**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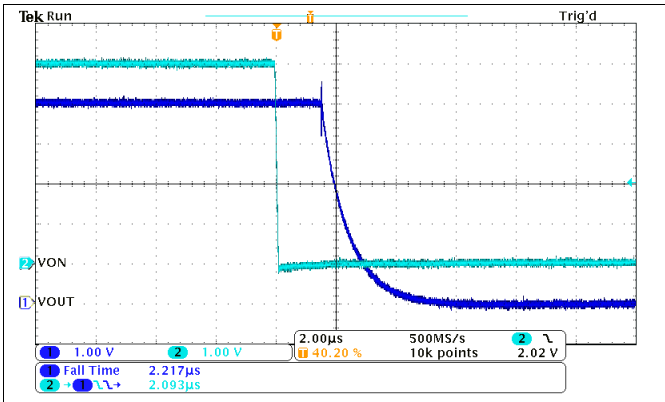
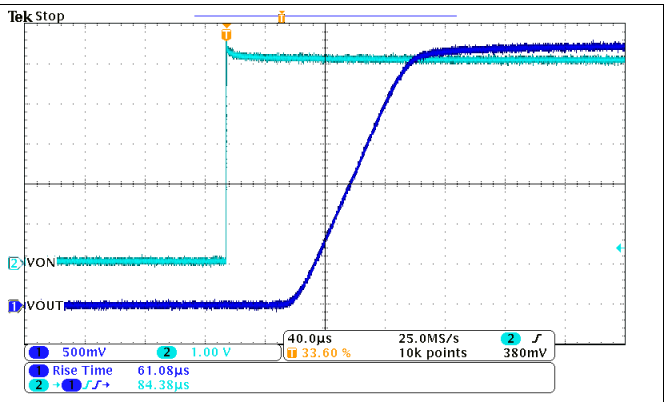
## Typical AC Characteristics (TPS22914B/15B) (continued)



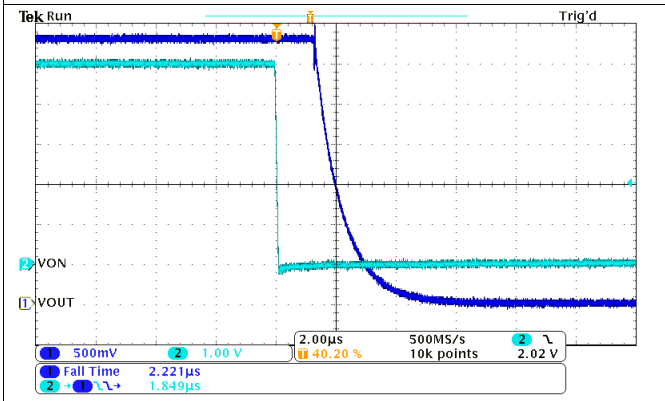

$V_{IN}$ = 5 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 19. $t_F$ at $V_{IN}$ = 5 V**



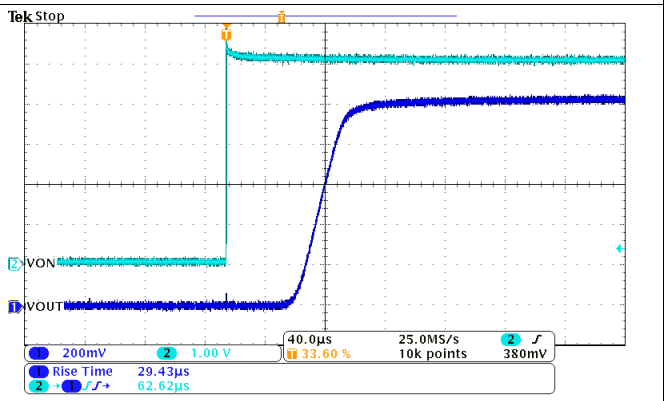

$V_{IN}$ = 3.3 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 20. $t_R$ at $V_{IN}$ = 3.3 V**



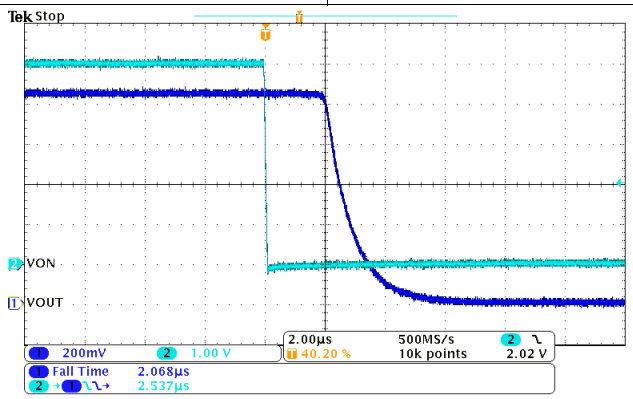

$V_{IN}$ = 3.3 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 21. $t_F$ at $V_{IN}$ = 3.3V**




$V_{IN}$ = 1.05 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

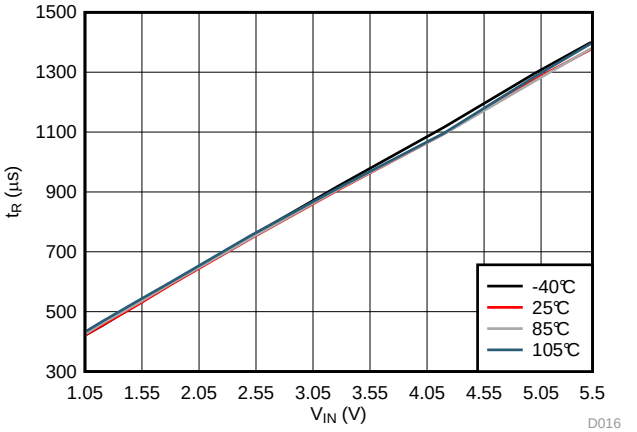
**Figure 22. $t_R$ at $V_{IN}$ = 1.05V**




$V_{IN}$ = 1.05 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

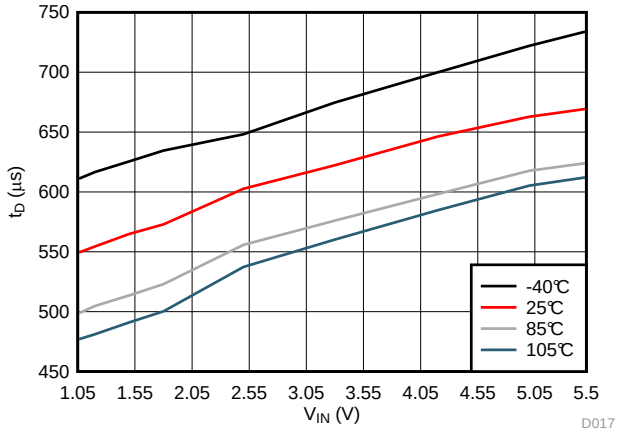
**Figure 23. $t_F$ at $V_{IN}$ = 1.05 V**

## 8.9 Typical AC Characteristics (TPS22914C/15C)



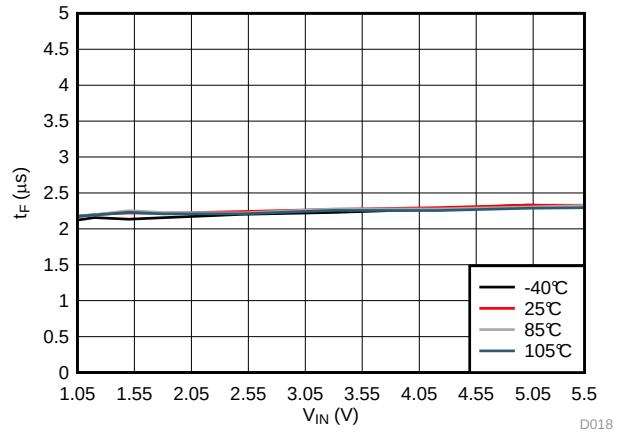

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 24. $t_R$ vs $V_{IN}$**



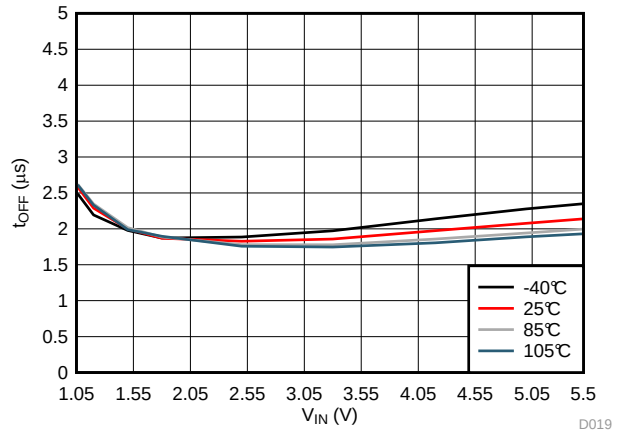

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 25. $t_D$ vs $V_{IN}$**



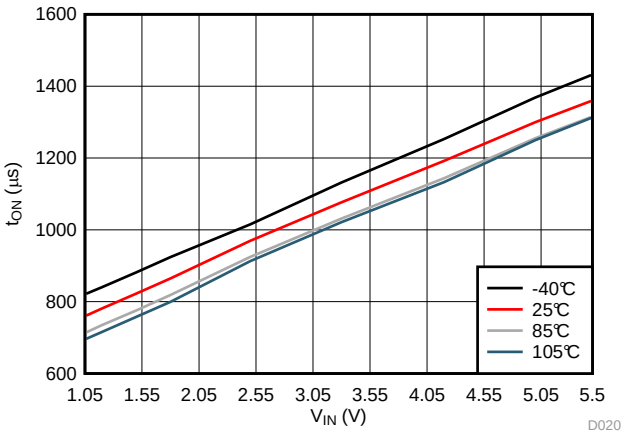

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 26. $t_F$ vs $V_{IN}$**



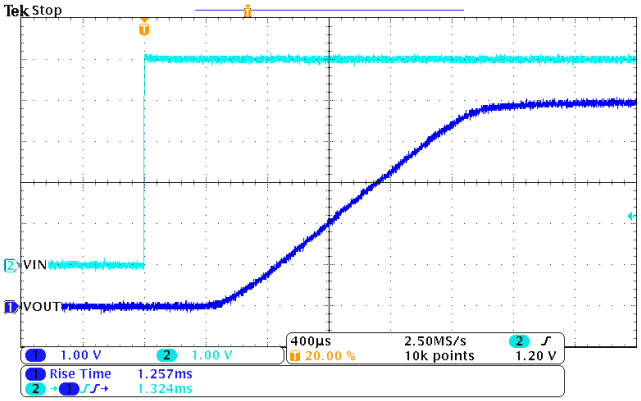

$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 27. $t_{OFF}$ vs $V_{IN}$**




$C_{IN}$ = 1 µF $R_L$ = 10 Ω $C_L$ = 0.1 µF

**Figure 28. $t_{ON}$ vs $V_{IN}$**




$V_{IN}$ = 5 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 29. $t_R$ at $V_{IN}$ = 5 V**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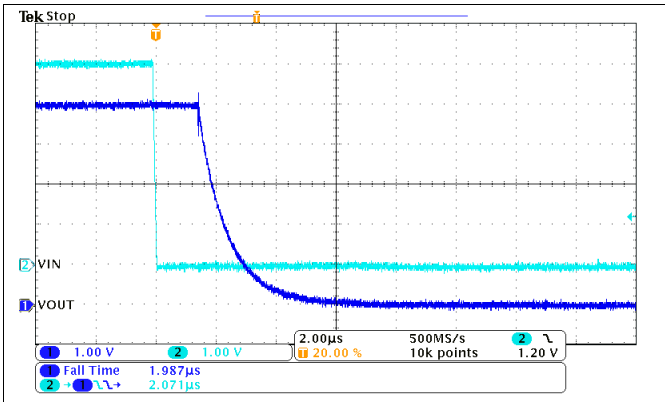
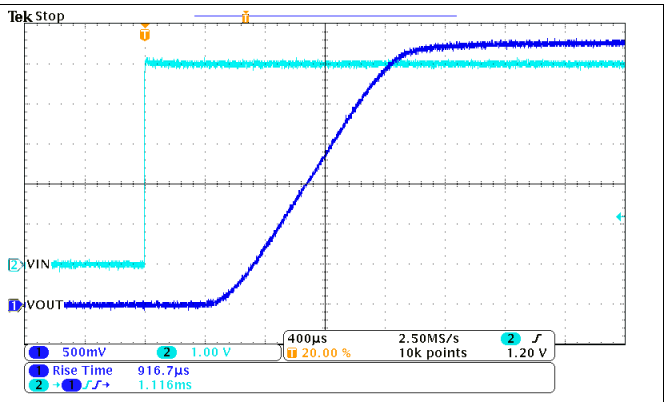
## Typical AC Characteristics (TPS22914C/15C) (continued)



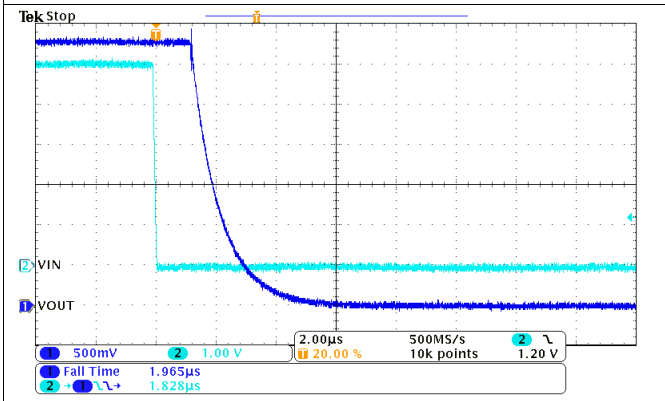

$V_{IN}$ = 5 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 30. $t_F$ at $V_{IN}$ = 5 V**



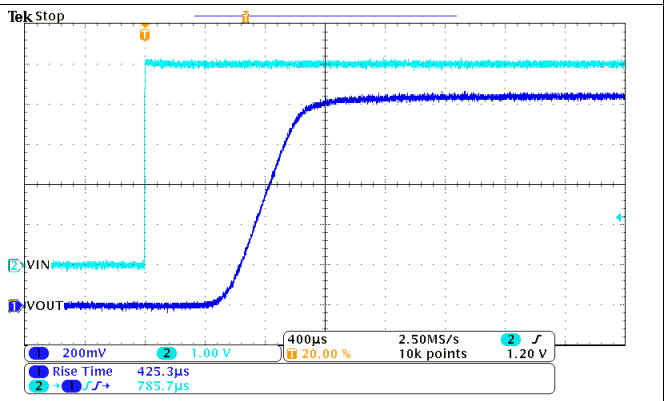

$V_{IN}$ = 3.3 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 31. $t_R$ at $V_{IN}$ = 3.3 V**



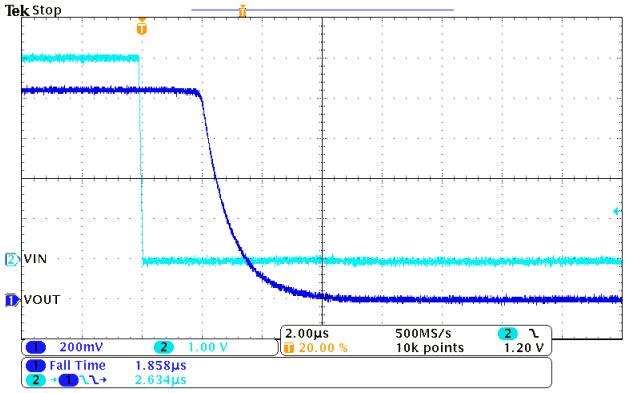

$V_{IN}$ = 3.3 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 32. $t_F$ at $V_{IN}$ = 3.3 V**




$V_{IN}$ = 1.05 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 33. $t_R$ at $V_{IN}$ = 1.05 V**




$V_{IN}$ = 1.05 V $C_{IN}$ = 1 µF $C_L$ = 0.1 µF
$R_L$ = 10 Ω

**Figure 34. $t_F$ at $V_{IN}$ = 1.05 V**

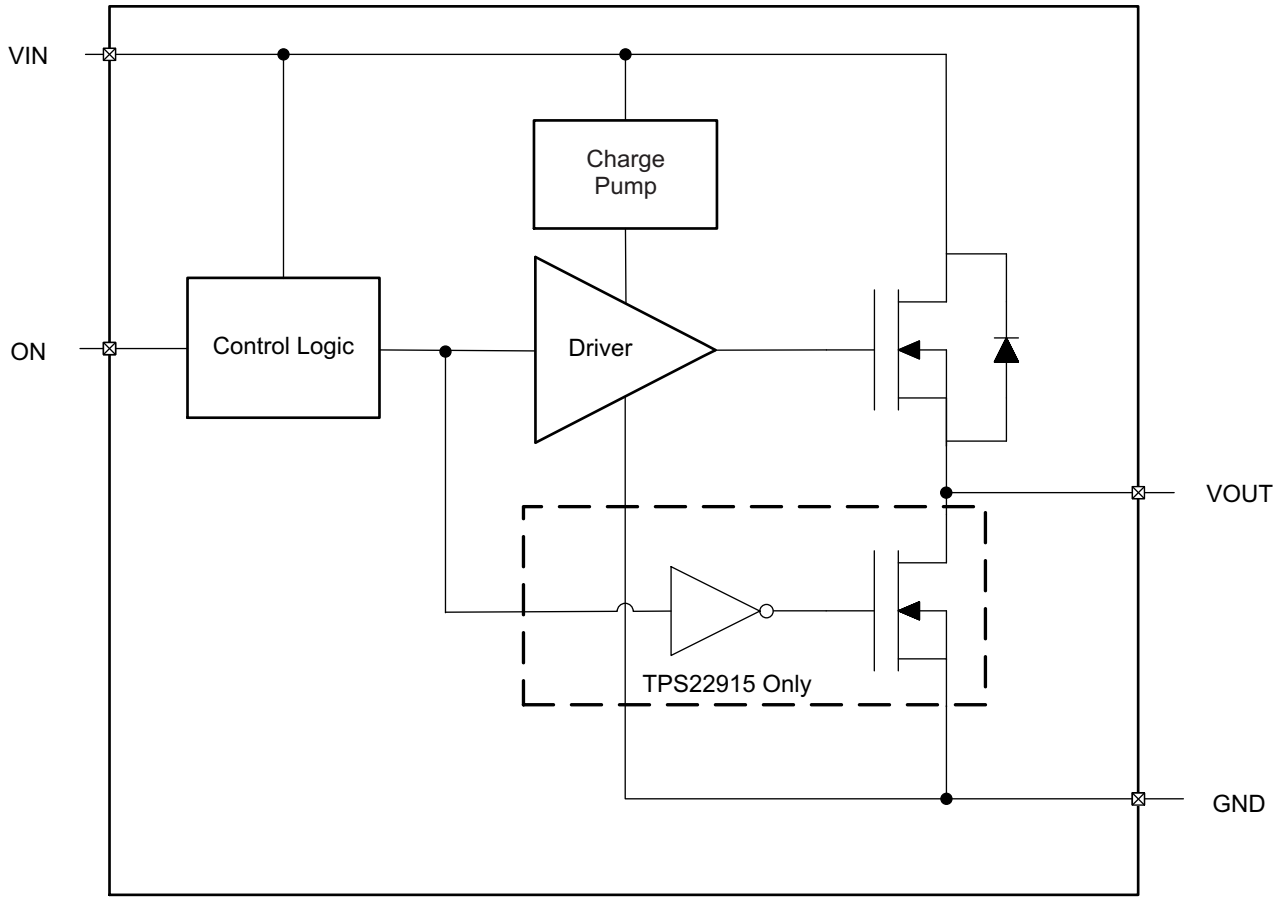
# 9 Detailed Description

## 9.1 Overview

The device is a 5.5-V, 2-A load switch in a 4-pin YFP package. To reduce voltage drop for low voltage and high current rails, the device implements an ultra-low resistance N-channel MOSFET which reduces the drop out voltage through the device.

The device has a controlled and fixed slew rate which helps reduce or eliminate power supply droop due to large inrush currents. During shutdown, the device has very low leakage currents, thereby reducing unnecessary leakages for downstream modules during standby. Integrated control logic, driver, charge pump, and output discharge FET eliminates the need for any external components, which reduces solution size and bill of materials (BOM) count.

## 9.2 Functional Block Diagram




## 9.3 Feature Description

### 9.3.1 On/Off Control

The ON pins control the state of the switch. Asserting ON high enables the switch. ON is active high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1.0-V or higher GPIO voltage. This pin cannot be left floating and must be driven either high or low for proper functionality.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## Feature Description (continued)

### 9.3.2 Input Capacitor ($C_{IN}$)

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns on into a discharged load capacitor or short-circuit, a capacitor needs to be placed between VIN and GND. A 1-µF ceramic capacitor, $C_{IN}$, placed close to the pins, is usually sufficient. Higher values of $C_{IN}$ can be used to further reduce the voltage drop during high-current application. When switching heavy loads, it is recommended to have an input capacitor about 10 times higher than the output capacitor to avoid excessive voltage drop.

### 9.3.3 Output Capacitor ($C_L$)

Due to the integrated body diode in the MOSFET, a $C_{IN}$ greater than $C_L$ is highly recommended. A $C_L$ greater than $C_{IN}$ can cause $V_{OUT}$ to exceed $V_{IN}$ when the system supply is removed. This could result in current flow through the body diode from VOUT to VIN. A $C_{IN}$ to $C_L$ ratio of 10 to 1 is recommended for minimizing $V_{IN}$ dip caused by inrush currents during startup.

## 9.4 Device Functional Modes

Table 1 describes the connection of the VOUT pin depending on the state of the ON pin.

**Table 1. VOUT Connection**

| ON | TPS22914 | TPS22915 |
|---|---|---|
| L | Open | GND |
| H | VIN | VIN |

# 10 Application and Implementation

**NOTE**

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 10.1 Application Information

This section will highlight some of the design considerations when implementing this device in various applications. A PSPICE model for this device is also available in the product page of this device.

## 10.2 Typical Application

This typical application demonstrates how the TPS22914 and TPS22915 can be used to power downstream modules.

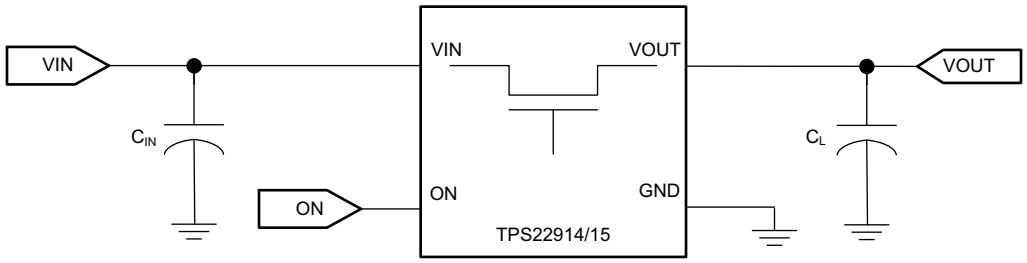


**Figure 35. Typical Application Schematic**

### 10.2.1 Design Requirements

For this design example, use the following as the input parameters:

| DESIGN PARAMETER | EXAMPLE VALUE |
|---|---|
| $V_{IN}$ | 5.0 V |
| Load Current | 2 A |


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### 10.2.2 Detailed Design Procedure

To begin the design process, the designer needs to know the following:

- $V_{IN}$ voltage
- Load Current

#### *10.2.2.1 VIN to VOUT Voltage Drop*

The VIN to VOUT voltage drop in the device is determined by the $R_{ON}$ of the device and the load current. The $R_{ON}$ of the device depends upon the VIN conditions of the device. Refer to the $R_{ON}$ specification of the device in the *Electrical Characteristics* table of this datasheet. Once the $R_{ON}$ of the device is determined based upon the VIN conditions, use Equation 1 to calculate the VIN to VOUT voltage drop:

$$\Delta V = I_{LOAD} \times R_{ON} \quad (1)$$

Where:

$\Delta V$ = voltage drop from VIN to VOUT
$I_{LOAD}$ = load current
$R_{ON}$ = On-resistance of the device for a specific $V_{IN}$

An appropriate $I_{LOAD}$ must be chosen such that the $I_{MAX}$ specification of the device is not violated.

#### *10.2.2.2 Inrush Current*

To determine how much inrush current will be caused by the $C_L$ capacitor, use Equation 2:

$$I_{INRUSH} = C_L \times \frac{dV_{OUT}}{dt} \quad (2)$$

Where:

$I_{INRUSH}$ = amount of inrush caused by $C_L$
$C_L$ = capacitance on VOUT
dt = rise time in VOUT during the ramp up of VOUT when the device is enabled
$dV_{OUT}$ = change in VOUT during the ramp up of VOUT when the device is enabled

An appropriate $C_L$ value should be placed on VOUT such that the $I_{MAX}$ and $I_{PLS}$ specifications of the device are not violated.

### 10.2.3 Application Curves

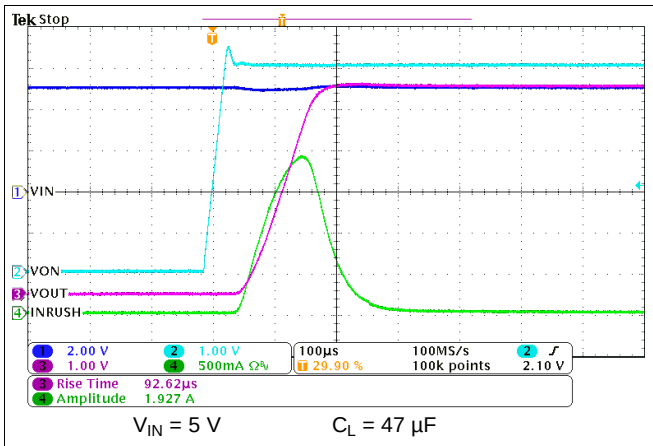


**Figure 36. TPS22914B/15B Inrush Current**

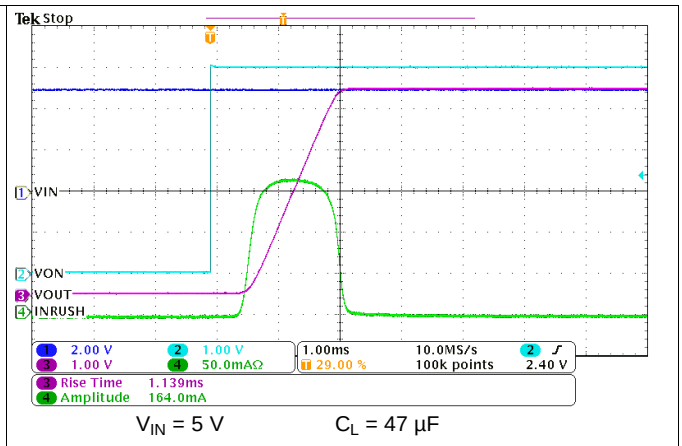


**Figure 37. TPS22914C/15C Inrush Current**

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# 11 Power Supply Recommendations

The device is designed to operate from a VIN range of 1.05 V to 5.5 V. This supply must be well regulated and placed as close to the device terminal as possible with the recommended 1-µF bypass capacitor. If the supply is located more than a few inches from the device terminals, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. If additional bulk capacitance is required, an electrolytic, tantalum, or ceramic capacitor of 1 µF may be sufficient.

# 12 Layout

## 12.1 Layout Guidelines

1. VIN and VOUT traces should be as short and wide as possible to accommodate for high current.
2. The VIN pin should be bypassed to ground with low ESR ceramic bypass capacitors. The typical recommended bypass capacitance is 1-µF ceramic with X5R or X7R dielectric. This capacitor should be placed as close to the device pins as possible.
3. The VOUT pin should be bypassed to ground with low ESR ceramic bypass capacitors. The typical recommended bypass capacitance is one-tenth of the VIN bypass capacitor of X5R or X7R dielectric rating. This capacitor should be placed as close to the device pins as possible.

### 12.1.1 Thermal Considerations

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces for VIN, VOUT, and GND helps minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance.

The maximum IC junction temperature should be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation, $P_{D(max)}$ for a given output current and ambient temperature, use Equation 3:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{\theta_{JA}} \quad (3)$$

Where:

$P_{D(MAX)}$ = maximum allowable power dissipation
$T_{J(MAX)}$ = maximum allowable junction temperature (125°C for the TPS22914/15)
$T_A$ = ambient temperature of the device
$\theta_{JA}$ = junction to air thermal impedance. Refer to the *Thermal Information* table. This parameter is highly dependent upon board layout.


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## 12.2 Layout Example

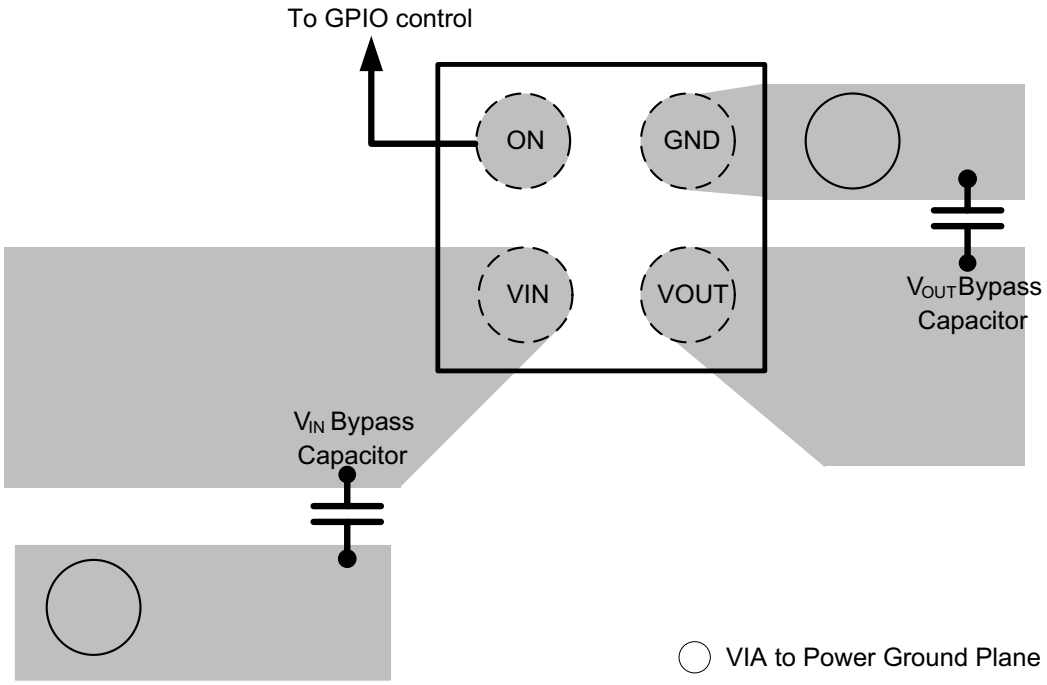


**Figure 38. Recommended Board Layout**

# 13 Device and Documentation Support

## 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 2. Related Links**

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|---|---|---|---|---|---|
| TPS22914B | Click here | Click here | Click here | Click here | Click here |
| TPS22914C | Click here | Click here | Click here | Click here | Click here |
| TPS22915B | Click here | Click here | Click here | Click here | Click here |
| TPS22915C | Click here | Click here | Click here | Click here | Click here |

## 13.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

**TI E2E™ Online Community** ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

## 13.3 Trademarks

E2E is a trademark of Texas Instruments.
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## 13.4 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 13.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.


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## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| TPS22914BYFPR | ACTIVE | DSBGA | YFP | 4 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S3 K | Samples |
| TPS22914BYFPT | ACTIVE | DSBGA | YFP | 4 | 250 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S3 K | Samples |
| TPS22914CYFPR | ACTIVE | DSBGA | YFP | 4 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S6 | Samples |
| TPS22914CYFPT | ACTIVE | DSBGA | YFP | 4 | 250 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S6 | Samples |
| TPS22915BYFPR | ACTIVE | DSBGA | YFP | 4 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S4 K | Samples |
| TPS22915BYFPT | ACTIVE | DSBGA | YFP | 4 | 250 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S4 K | Samples |
| TPS22915CYFPR | ACTIVE | DSBGA | YFP | 4 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S7 | Samples |
| TPS22915CYFPT | ACTIVE | DSBGA | YFP | 4 | 250 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | S7 | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**(4)** There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

**(5)** Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**(6)** Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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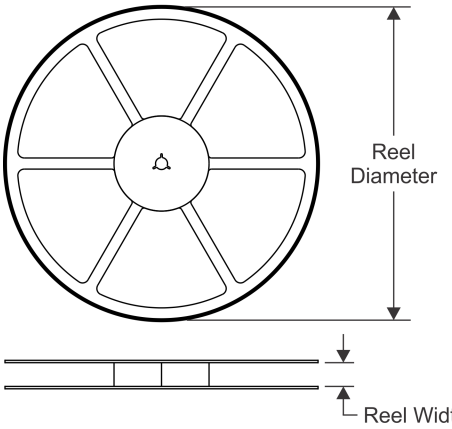
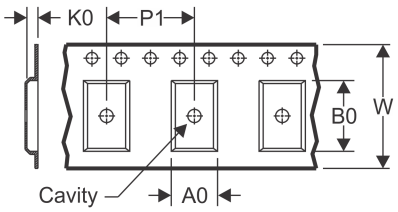
## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

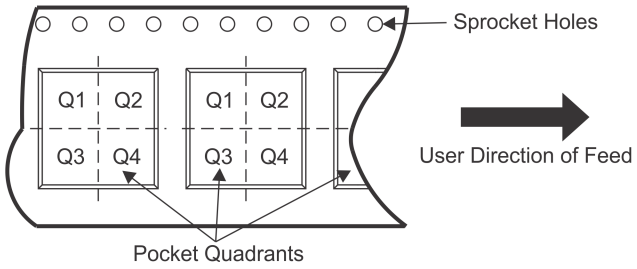



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

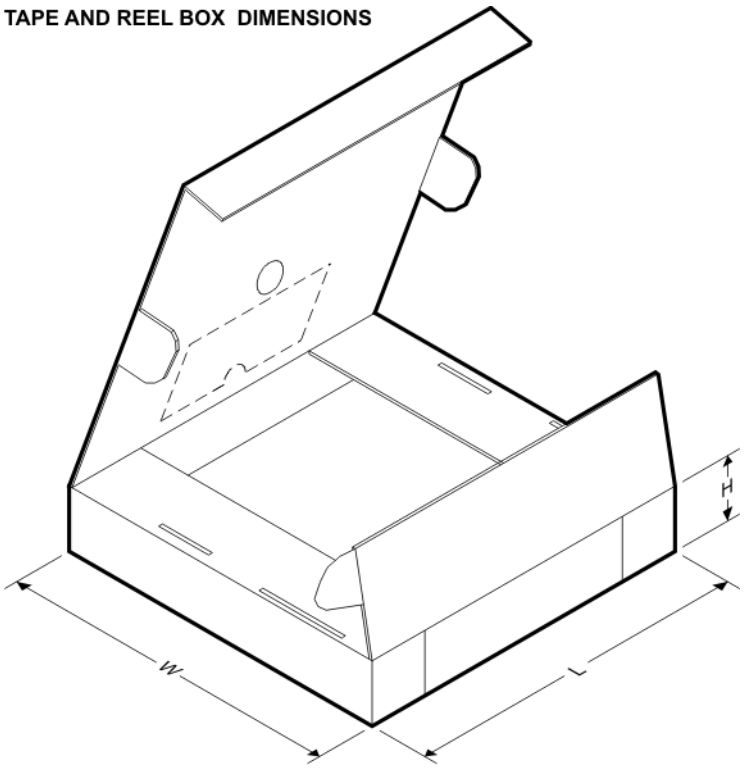
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| TPS22914BYFPR | DSBGA | YFP | 4 | 3000 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22914BYFPR | DSBGA | YFP | 4 | 3000 | 178.0 | 9.2 | 0.85 | 0.85 | 0.59 | 4.0 | 8.0 | Q1 |
| TPS22914BYFPT | DSBGA | YFP | 4 | 250 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22914BYFPT | DSBGA | YFP | 4 | 250 | 178.0 | 9.2 | 0.85 | 0.85 | 0.59 | 4.0 | 8.0 | Q1 |
| TPS22914CYFPR | DSBGA | YFP | 4 | 3000 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22914CYFPT | DSBGA | YFP | 4 | 250 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22915BYFPR | DSBGA | YFP | 4 | 3000 | 178.0 | 9.2 | 0.85 | 0.85 | 0.59 | 4.0 | 8.0 | Q1 |
| TPS22915BYFPR | DSBGA | YFP | 4 | 3000 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22915BYFPT | DSBGA | YFP | 4 | 250 | 178.0 | 9.2 | 0.85 | 0.85 | 0.59 | 4.0 | 8.0 | Q1 |
| TPS22915CYFPR | DSBGA | YFP | 4 | 3000 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |
| TPS22915CYFPT | DSBGA | YFP | 4 | 250 | 180.0 | 8.4 | 0.85 | 0.85 | 0.64 | 4.0 | 8.0 | Q1 |

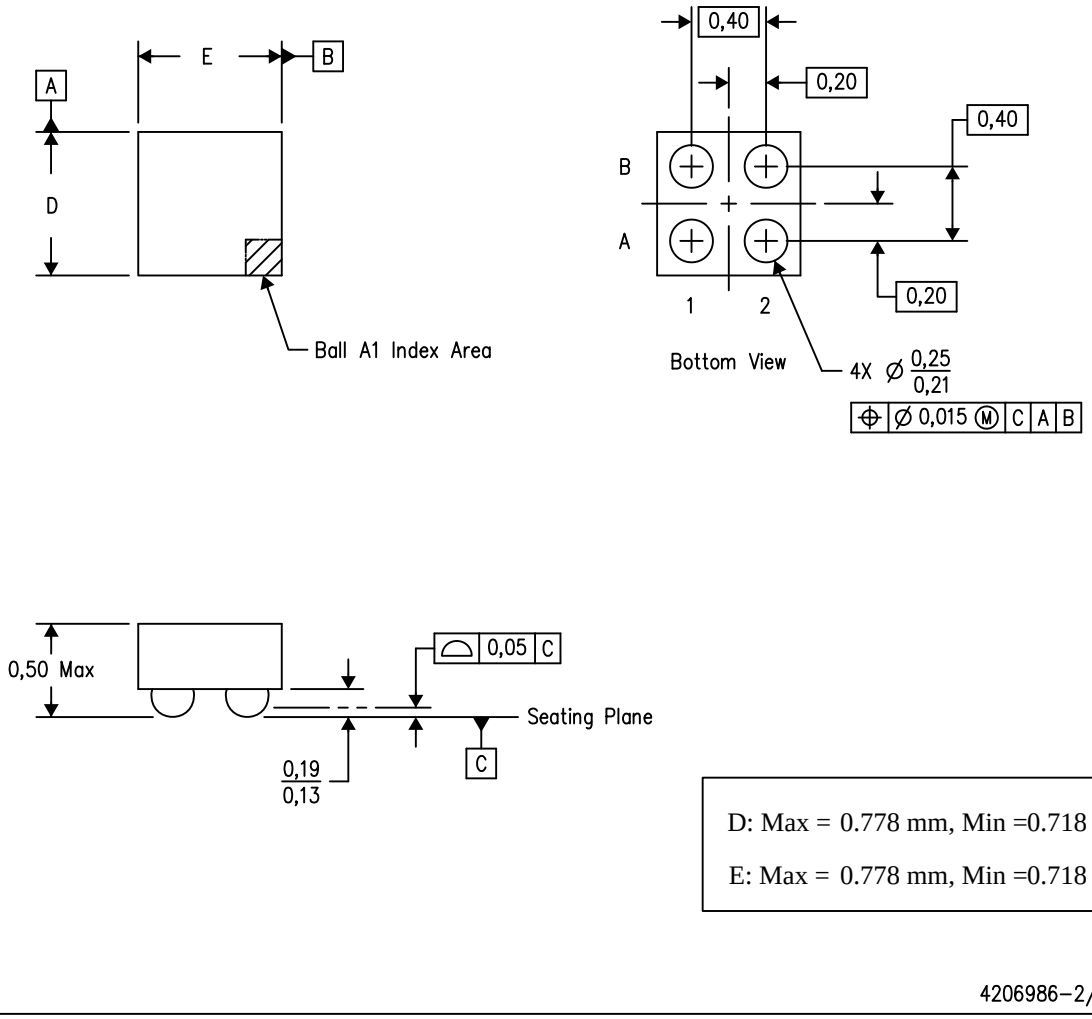
**TAPE AND REEL BOX DIMENSIONS**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| TPS22914BYFPR | DSBGA | YFP | 4 | 3000 | 182.0 | 182.0 | 20.0 |
| TPS22914BYFPR | DSBGA | YFP | 4 | 3000 | 220.0 | 220.0 | 35.0 |
| TPS22914BYFPT | DSBGA | YFP | 4 | 250 | 182.0 | 182.0 | 20.0 |
| TPS22914BYFPT | DSBGA | YFP | 4 | 250 | 220.0 | 220.0 | 35.0 |
| TPS22914CYFPR | DSBGA | YFP | 4 | 3000 | 182.0 | 182.0 | 20.0 |
| TPS22914CYFPT | DSBGA | YFP | 4 | 250 | 182.0 | 182.0 | 20.0 |
| TPS22915BYFPR | DSBGA | YFP | 4 | 3000 | 220.0 | 220.0 | 35.0 |
| TPS22915BYFPR | DSBGA | YFP | 4 | 3000 | 182.0 | 182.0 | 20.0 |
| TPS22915BYFPT | DSBGA | YFP | 4 | 250 | 220.0 | 220.0 | 35.0 |
| TPS22915CYFPR | DSBGA | YFP | 4 | 3000 | 182.0 | 182.0 | 20.0 |
| TPS22915CYFPT | DSBGA | YFP | 4 | 250 | 182.0 | 182.0 | 20.0 |

YFP (S–XBGA–N4) DIE–SIZE BALL GRID ARRAY




NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments

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